

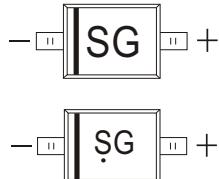
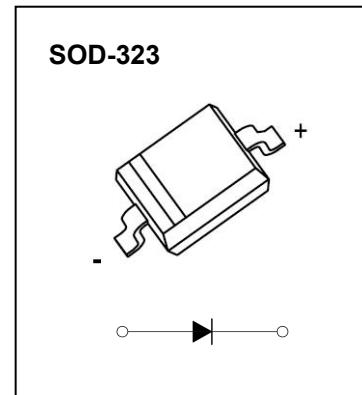


## SCHOTTKY BARRIER DIODE

## FEATURES

- Low Forward Voltage Drop
- Guard Ring Die Construction for Transient Protection
- Ideal for Low Logic Level Applications
- Low Capacitance
- Also Available in Lead Free Version

## MARKING: SG



The marking bar indicates the cathode  
Solid dot = Green molding compound device, if none, the normal device

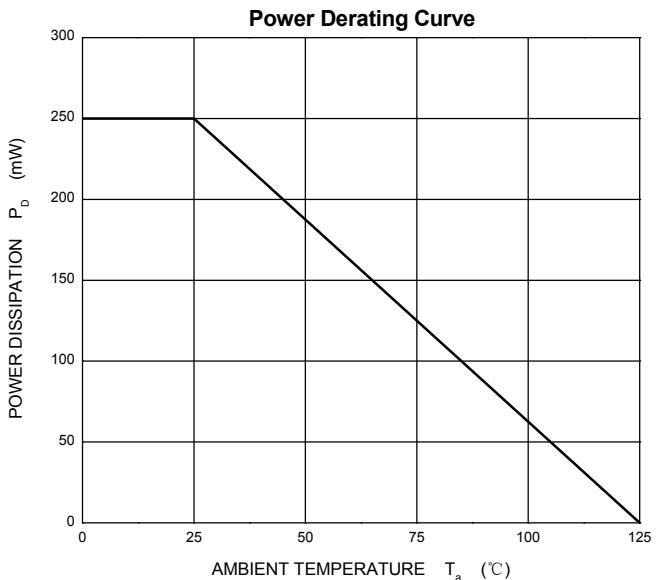
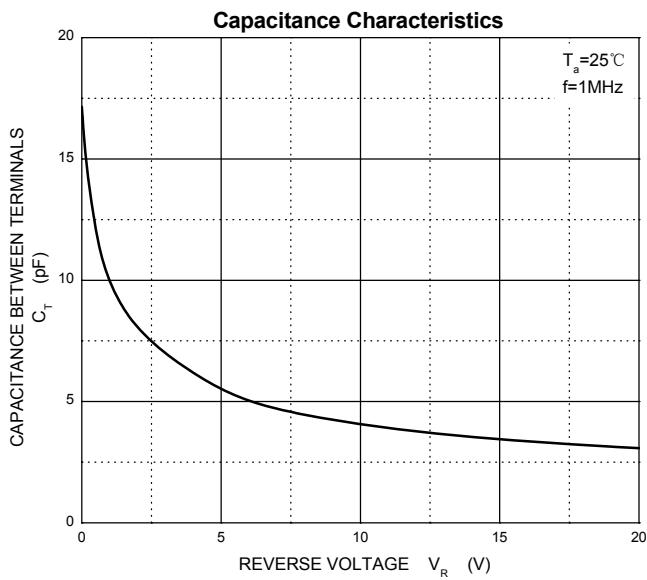
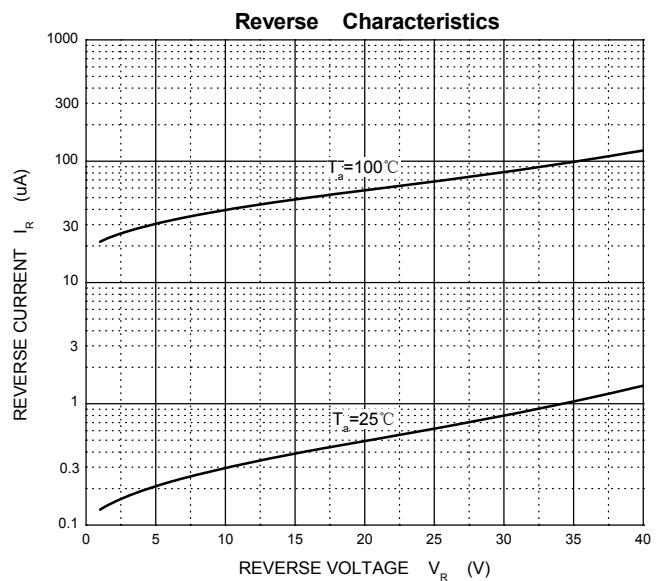
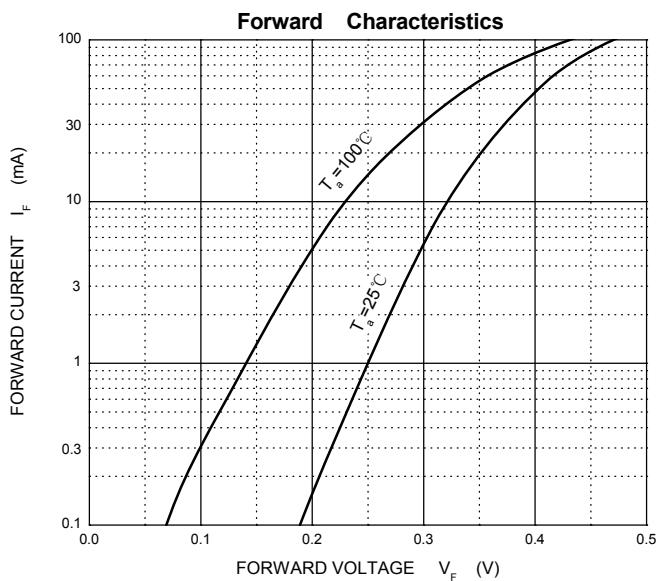
## Maximum Ratings and Electrical Characteristics, Single Diode @Ta=25°C

Parameter	Symbol	Limit		Unit
Non-repetitive peak reverse voltage	V <sub>RM</sub>	30		V
Forward current	I <sub>FM</sub>	100		mA
Non-repetitive Peak Forward Surge Current @t = 8 .3ms	I <sub>FSM</sub>	2		A
Power dissipation T <sub>c</sub> =25°C	P <sub>tot</sub>	250		mW
Thermal resistance junction to ambient	T <sub>eJA</sub>	400		°C/W
Junction temperature	T <sub>J</sub>	125		°C
Storage temperature	T <sub>STG</sub>	-55~+150		°C

## Electrical Ratings @Ta=25°C

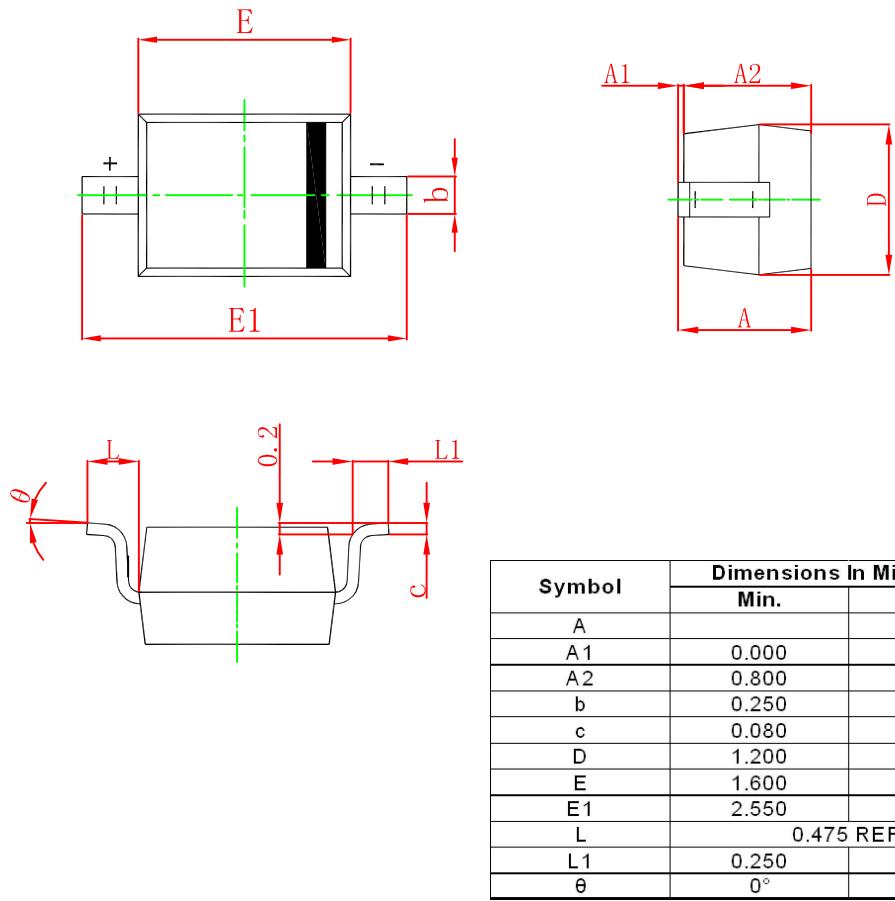
Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Reverse breakdown voltage	V <sub>R</sub>	30			V	I <sub>R</sub> =100μA
Forward voltage	V <sub>F</sub>		300		mV	I <sub>F</sub> =2mA
			360			I <sub>F</sub> =15mA
			430	550		I <sub>F</sub> =50mA
			500	800		I <sub>F</sub> =100mA
Reverse current	I <sub>R</sub>			1	μA	V <sub>R</sub> =25V
Capacitance between terminals	C <sub>T</sub>		7		pF	V <sub>R</sub> =10V,f=1MHz

### Typical Characteristics

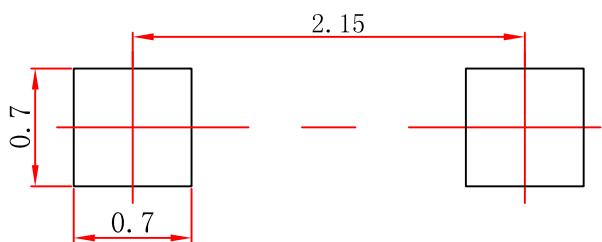




## SOD-323 Package Outline Dimensions



## SOD-323 Suggested Pad Layout

**Note:**

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05$ mm.
3. The pad layout is for reference purposes only.